FIG.1

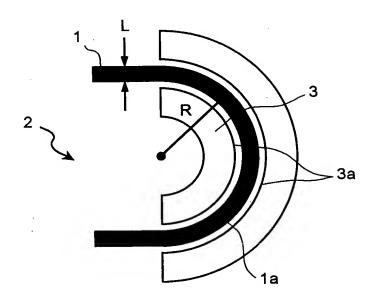
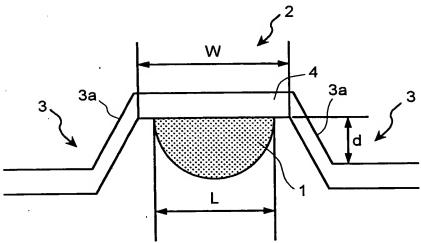
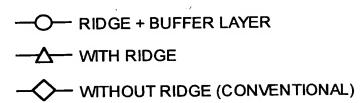


FIG.2







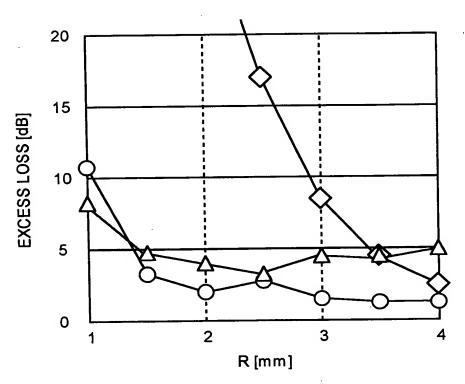


FIG.4A
TI PATTERN FORMATION

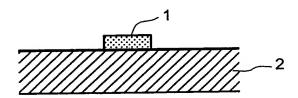


FIG.4B

THERMAL DIFFUSION

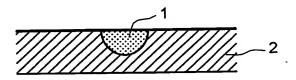


FIG.4C

ETCHING

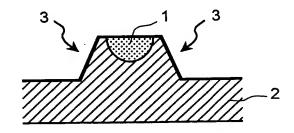


FIG.4D

BUFFER LAYER FORMATION

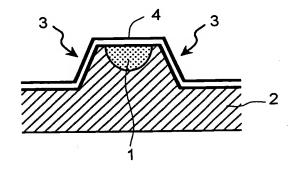


FIG.5

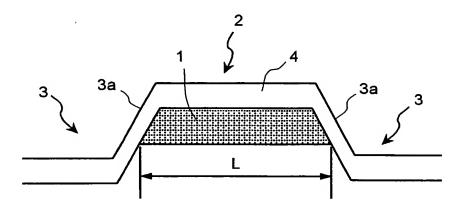
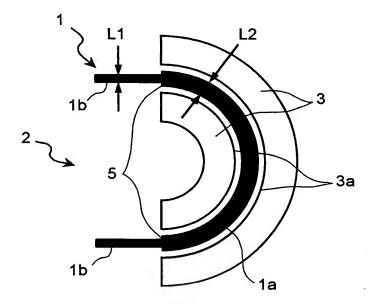


FIG.6



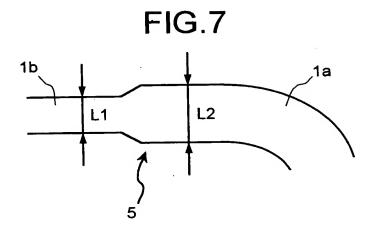


FIG.8

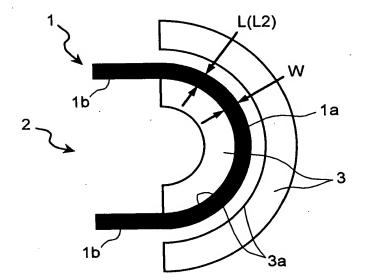


FIG.9

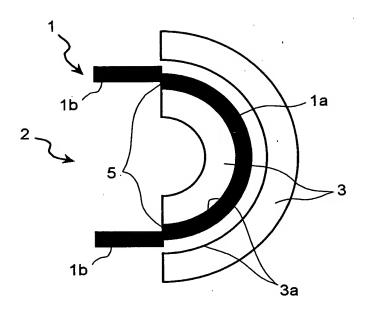


FIG.10

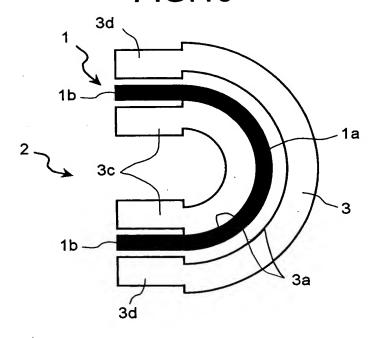


FIG.11

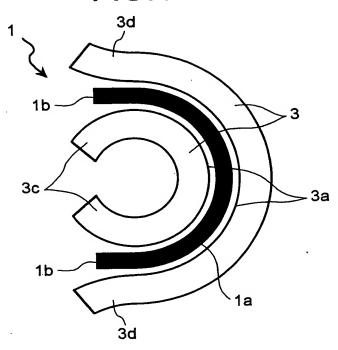
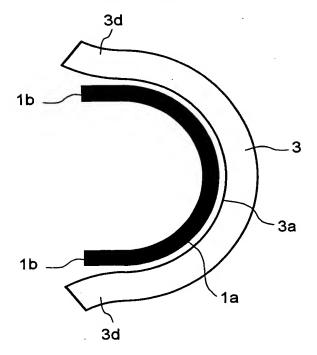


FIG.12



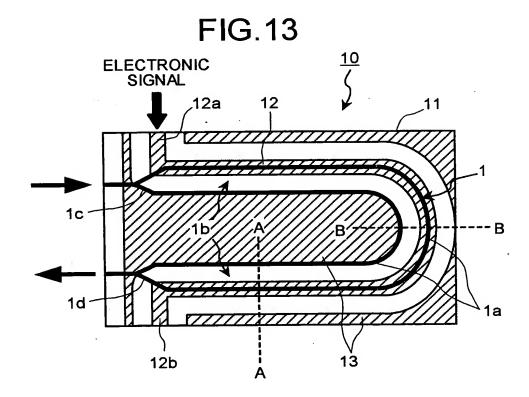


FIG.14A

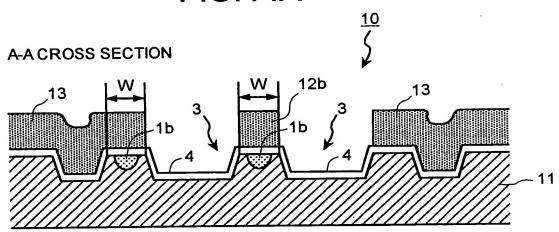


FIG.14B

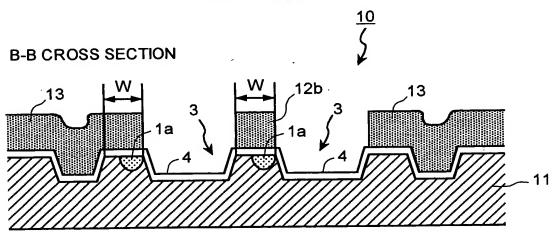


FIG.15

